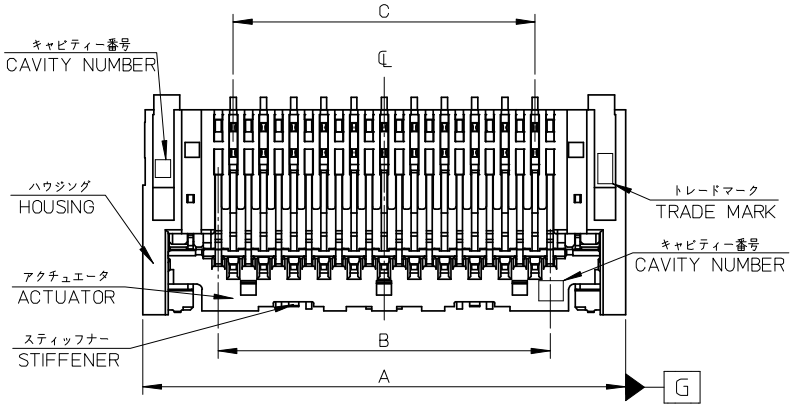
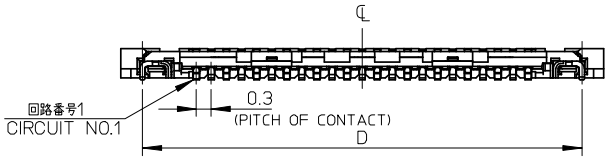
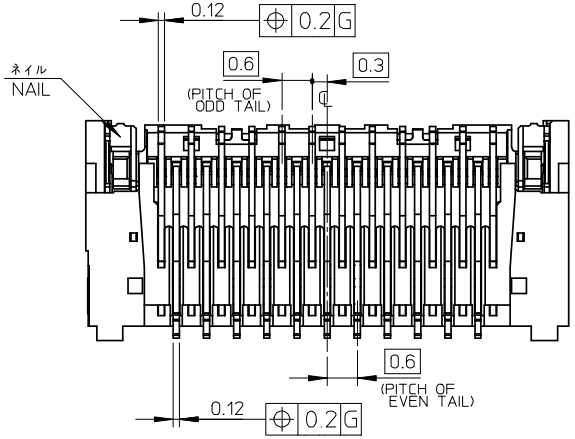
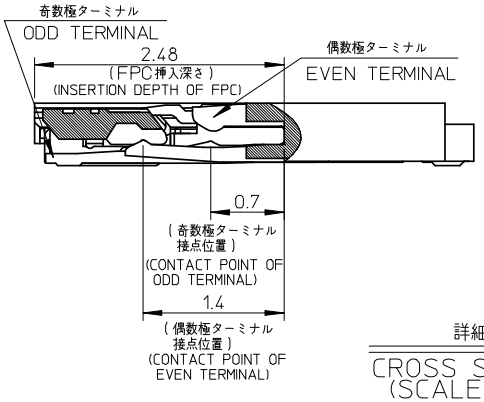
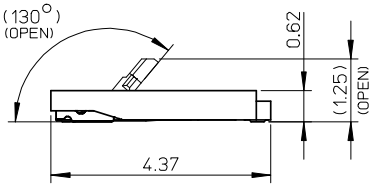


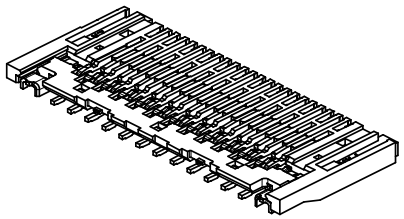




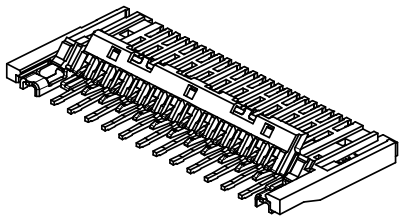


詳細図
CROSS SECTION
(SCALE 20:1)





アクチュエータ CLOSE
(製品納入状態)



アクチュエータ OPEN

16.54	13.8	14.4	17.4	502761-4900	502761-4909	49
11.74	9	9.6	12.6	502761-3300	502761-3309	33
D	C	B	A	オーダー番号 ORDER NO. (EMBOSSED TAPE)	製品番号 MATERIAL NO.	極数 CIRCUITS

REVISED
EC NO: J2008-4277 2008/06/17
DRWN:TRSUZUKI 2008/06/18
CHKD:KMORIKAWA 2008/06/18
APPR:KMORIKAWA 2008/06/18
DESCRIPTION
REV A

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR ±1 °	

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY	SCALE: 10:1	DESIGN UNITS: METRIC	THIRD ANGLE PROJECTION
DRAWN BY: TRSUZUKI DATE: 2008/06/11	TITLE: 0.3 FPC CONN (H=0.62) HSG ASSY BOTTOM CONTACT GOLD WITH NICKEL BARRIER		
CHECKED BY: KMORIKAWA DATE: 2008/06/11			
APPROVED BY: HHIRATA DATE: 2008/06/11	molex MOLEX INCORPORATED		
MATERIAL NO.: SEE CHART	DOCUMENT NO.: SD-502761-001	SHEET NO.: 1 OF 3	

SIZE A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

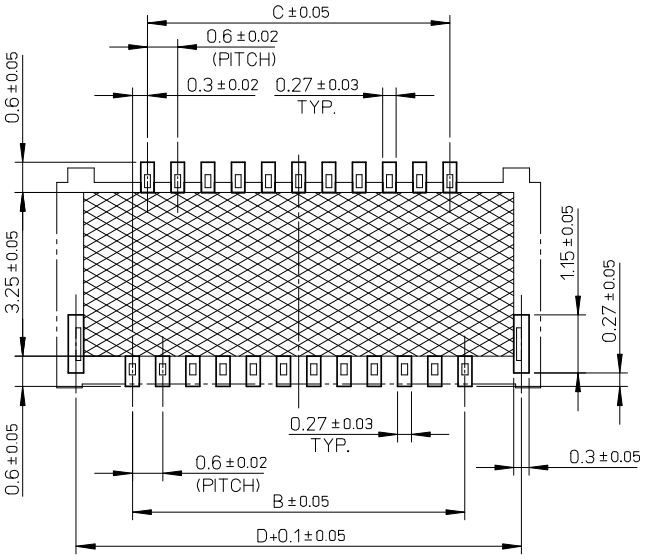
注記 NOTES:

1.使用材料 MATERIAL
ハウジング ： 液晶ポリマー ガラス充填 UL94V-0（黒）
HOUSING : LIQUID CRYSTAL POLYMER (GLASS FILLED) UL94V-0 (COLOR:BLACK)
アクチュエータ ： 液晶ポリマー ガラス充填 UL94V-0（灰色）
ACTUATOR : LIQUID CRYSTAL POLYMER (GLASS FILLED) UL94V-0 (COLOR:GRAY)
ターミナル ： 銅ニッケルスズ合金
TERMINAL : COPPER NICKEL TIN ALOY
ネイル ： リン青銅
FITTING NAIL : PHOSPHOR-BRONZE
スティッフナー ： ステンレス鋼
STIFFENER : STAINLESS STEEL

2.メッキ仕様 PLATING
ターミナル TERMINAL
接点部 ： 金メッキ
CONTACT AREA : GOLD
半田付け部 ： 金メッキ
SOLDER TAIL AREA : GOLD
下地メッキ ： ニッケルメッキ
UNDER PLATING : NICKEL
ネイル FITTING NAIL
スズメッキ
TIN
下地メッキ ： ニッケルメッキ
UNDER PLATING : NICKEL

3.ソルダーテール半田付け面、及びネイル半田付け面の平坦度：0.15MAX.
COPLANARITY OF SOLDER TAILS AND FITTING NAILS TO BE 0.15mm MAX.

4.ELV 及び RoHS適合品
ELV AND RoHS COMPLIANT



：パターン及び半田禁止エリア
:PATTERN AND SOLDER PROHIBITION AREA

推奨基板寸法
RECOMMENDED P.C.B. PATTERN LAYOUT

推奨メタルマスク仕様について：
厚さ：0.11mm、開口率：弊社推奨パターンに対し60%
ABOUT : METAL MASK SPECIFICATION
RECOMMENDED THICKNESS : 0.11mm
THE RECOMMENDED APERTURE RATE SHALL BE 60% USING OUR RECOMMENDED P.C.B. PATTERN LAYOUT.

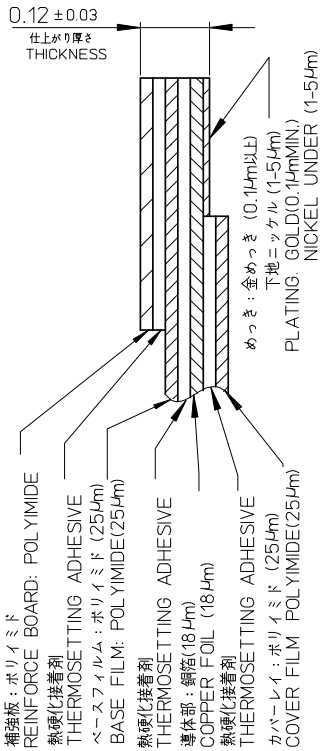
SEE SHEET 1			
EC NO: J2008-4277			
DRWN:TRSUZUKI	2008/06/17		
CH'KD:KMORIKAWA	2008/06/18		
APPR:KMORIKAWA	2008/06/18		
DESCRIPTION			
A			
REV			

GENERAL TOLERANCES (UNLESS SPECIFIED)

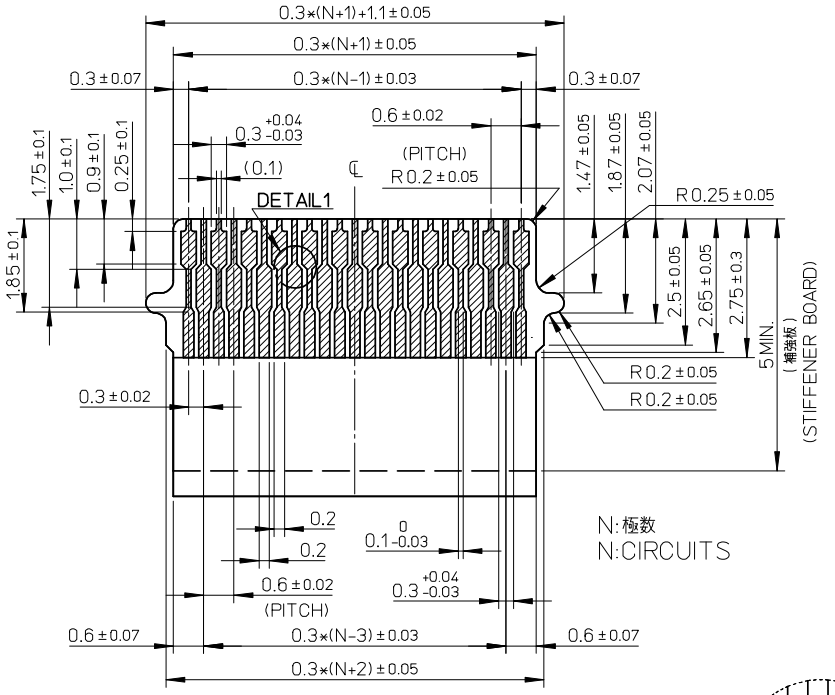
10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR ±1 °	

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

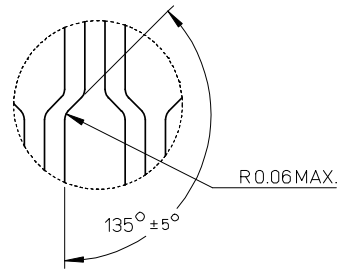
DIMENSION STYLE: MM ONLY	SCALE: 10:1	DESIGN UNITS: METRIC	THIRD ANGLE PROJECTION
DRAWN BY: TRSUZUKI DATE: 2008/06/11	TITLE: 0.3 FPC CONN (H=0.62) HSG ASSY BOTTOM CONTACT GOLD WITH NICKEL BARRIER		
CHECKED BY: KMORIKAWA DATE: 2008/06/11			
APPROVED BY: HHIRATA DATE: 2008/06/11	MOLEX INCORPORATED		
MATERIAL NO.: SEE SHEET 1	DOCUMENT NO.: SD-502761-001	SHEET NO.: 2 OF 3	
SIZE: A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



FPC構成推奨仕様
STRUCTURE OF FPC



適合する金めっきFPC推奨寸法
APPLICABLE FPC OF GOLD PLATING
RECOMMENDED DIMENSION
(仕上がり厚さ：0.12± 0.03)
(THICKNESS:0.12± 0.03)



DETAIL1
Scale 40:1

FPCについて：
抜き方向は、導体側から補強板側を推奨致します。
補強フィルム材質は、ポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、
染み出しが無い様、お願い致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFNER FILM SIDE.
RECOMMENDED MATERIAL:
STIFFENER FILM . POLYIMIDE
BONDING AGENT : THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND
BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE
CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

SEE SHEET 1
EC NO: J2008-4277
DRWN:TRSUZUKI 2008/06/17
CH'KD:KMORIKAWA 2008/06/18
APPR:KMORIKAWA 2008/06/18
DESCRIPTION
A
REV

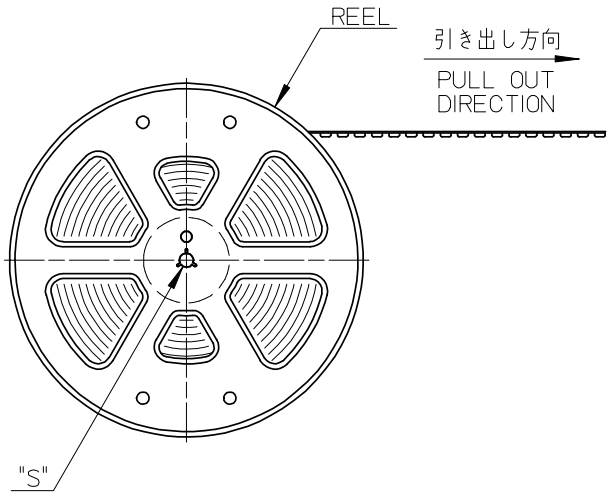
GENERAL TOLERANCES (UNLESS SPECIFIED)

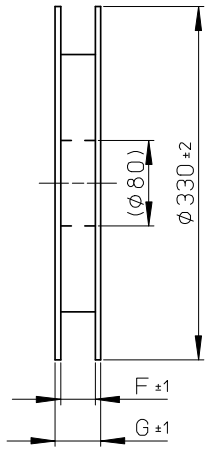
10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR ±1 °	

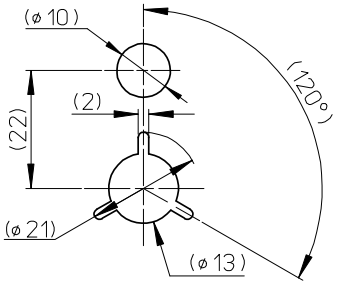
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	MM ONLY
SCALE	10:1
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION
DRAWN BY / DATE	TRSUZUKI 2008/06/11
CHECKED BY / DATE	KMORIKAWA 2008/06/11
APPROVED BY / DATE	HHIRATA 2008/06/11
MATERIAL NO.	SEE SHEET 1
TITLE	0.3 FPC CONN (H=0.62) HSG ASSY BOTTOM CONTACT GOLD WITH NICKEL BARRIER
	MOLEX INCORPORATED
DOCUMENT NO.	SD-502761-001
SHEET NO.	3 OF 3
SIZE	A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION



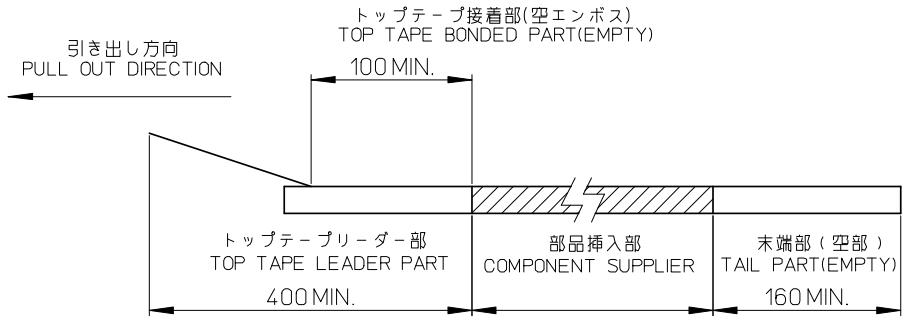




DETAIL S

NOTES

1. 製品詳細寸法につきましては、SD-502761-001 を参照ください。
   RE DETAILED DIMENSION, SEE SD-502761-001
2. 梱包数量：3000個/リール
   NUMBER OF CONNECTORS : 3000PCS/REEL
3. リードテープの長さ
   LEAD TAPE LENGTH



4. 材料(MATERIAL)
   キャリアテープ(CARRIER TAPE) : ポリスチレン(POLYSTYRENE)
   トップテープ(TOP TAPE) : PET, PE, PEF
   リール(REEL) : ポリスチレン(POLYSTYRENE)<リサイクル材を含む>
   <RECYCLE MATERILAL CONTAINED>
5. ELV 及び RoHS適合品
   ELV AND RoHS COMPLIANT.

RELEASED 2008/06/13
EC NO: J2008-3700
DRWN:TRSUZUKI 2008/06/13
CH'KD:KMORIKAWA 2008/06/13
APPR:KMORIKAWA 2008/06/16
DESCRIPTION
REV 0

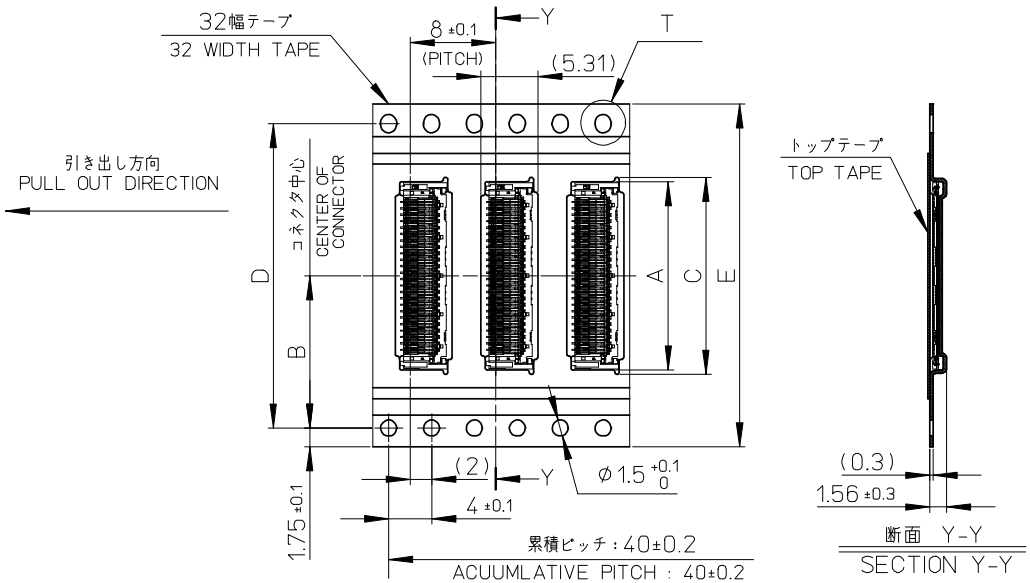
GENERAL TOLERANCES (UNLESS SPECIFIED)	
10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR ±1 °	

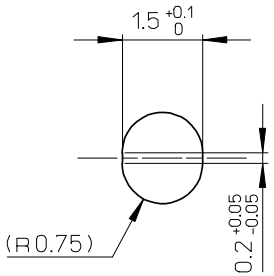
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	MM ONLY
SCALE	---
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION
DRAWN BY	TRSUZUKI
DATE	2008/06/11
CHECKED BY	KMORIKAWA
DATE	2008/06/11
APPROVED BY	HHIRATA
DATE	2008/06/11
MATERIAL NO.	SEE SHEET 2
TITLE	0.3 FPC CONN (H=0.62) EMBOSSED TAPE PACKAGE GOLD WITH NICKEL BARRIER
	MOLEX INCORPORATED
DOCUMENT NO.	SD-502761-002
SHEET NO.	1 OF 2
SIZE	A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

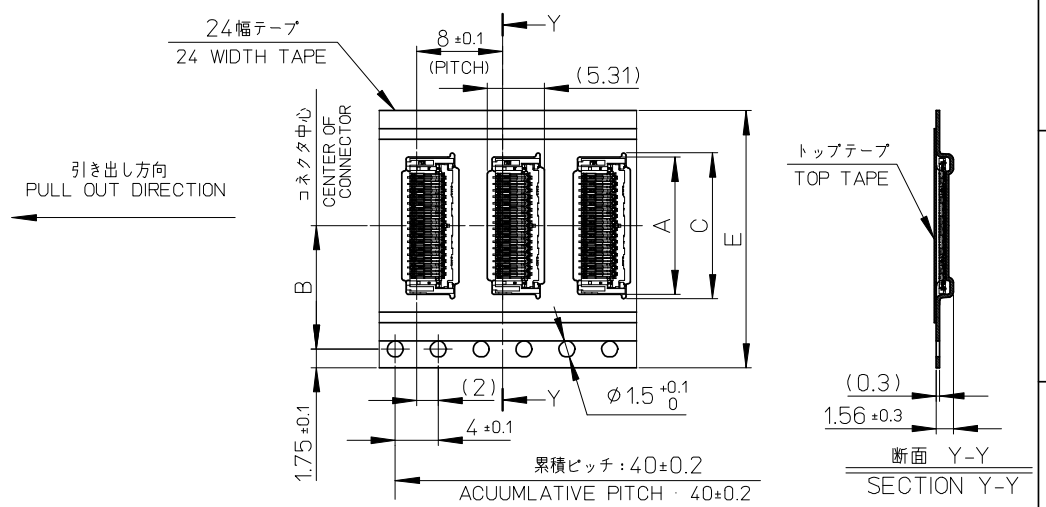
キャリアテープ幅：32mm品





T部詳細
DETAIL T

キャリアテープ幅：24mm品



G	F	E キャリアテープ幅 CARRIER TAPE WIDTH	D	(C)	(B)	(A)	製品番号 MATERIAL NO.	極数 CIRCUITS
37.4	33.4	32±0.3	28.4	18.4	14.2	17.6	502761-4900	49
29.4	25.4	24±0.3	---	13.6	11.5	12.8	502761-3300	33

SEE SHEET 1
EC NO: J2008-3700 2008/06/13
DRWN:TRSUZUKI 2008/06/13
CH'KD:KMORIKAWA 2008/06/13
APPR:KMORIKAWA 2008/06/16
DESCRIPTION
REV 0

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±1 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: ---
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: TRSUZUKI DATE: 2008/06/11
CHECKED BY: KMORIKAWA DATE: 2008/06/11
APPROVED BY: HHIRATA DATE: 2008/06/11

TITLE: 0.3 FPC CONN (H=0.62) EMBOSSED TAPE PACKAGE GOLD WITH NICKEL BARRIER

molex MOLEX INCORPORATED

MATERIAL NO.: SEE CHART
DOCUMENT NO.: SD-502761-002
SHEET NO.: 2 OF 2
SIZE: A3

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